



SOT1337-1

plastic, extremely thin small outline package; 10 terminals;
0.4 mm pitch; 1.3 mm x 1.6 mm x 0.5 mm body

30 January 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN10
Package type industry code	XQFN10
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-288
Mounting method type	S (surface mount)
Issue date	11-9-2012
Manufacturer package code	SOT1337

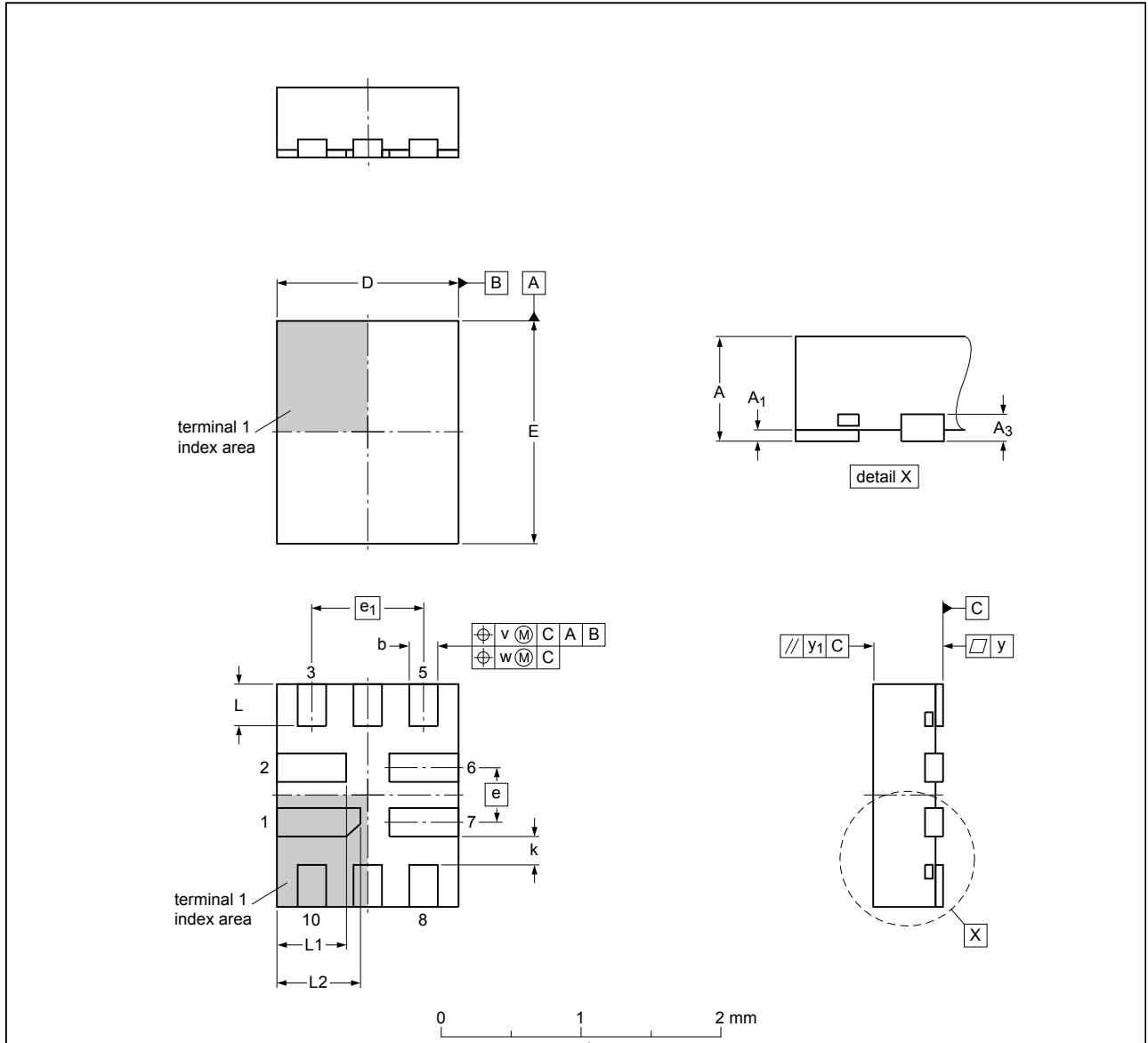
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.25	-	1.3	1.35	mm
E	package width	1.55	-	1.6	1.65	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	10	-	

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2. Package outline

XQFN10: plastic extremely thin small outline package; no leads; 10 terminals; body 1.3 x 1.6 x 0.5 mm **SOT1337-1**



Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A	A ₁	A ₃	b	D	E	e	e ₁	k	L	L ₁	L ₂	v	w	y	y ₁
max	0.5	0.05	0.127	0.25	1.35	1.65				0.35	0.55	0.65				
mm nom				0.20	1.30	1.60	0.4	0.8		0.30	0.50	0.60	0.1	0.05	0.05	0.05
min		0.00	0.050	0.15	1.25	1.55			0.2	0.25	0.45	0.55				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1337-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1337-1	---	MO-288	---		-12-08-28- 12-09-11

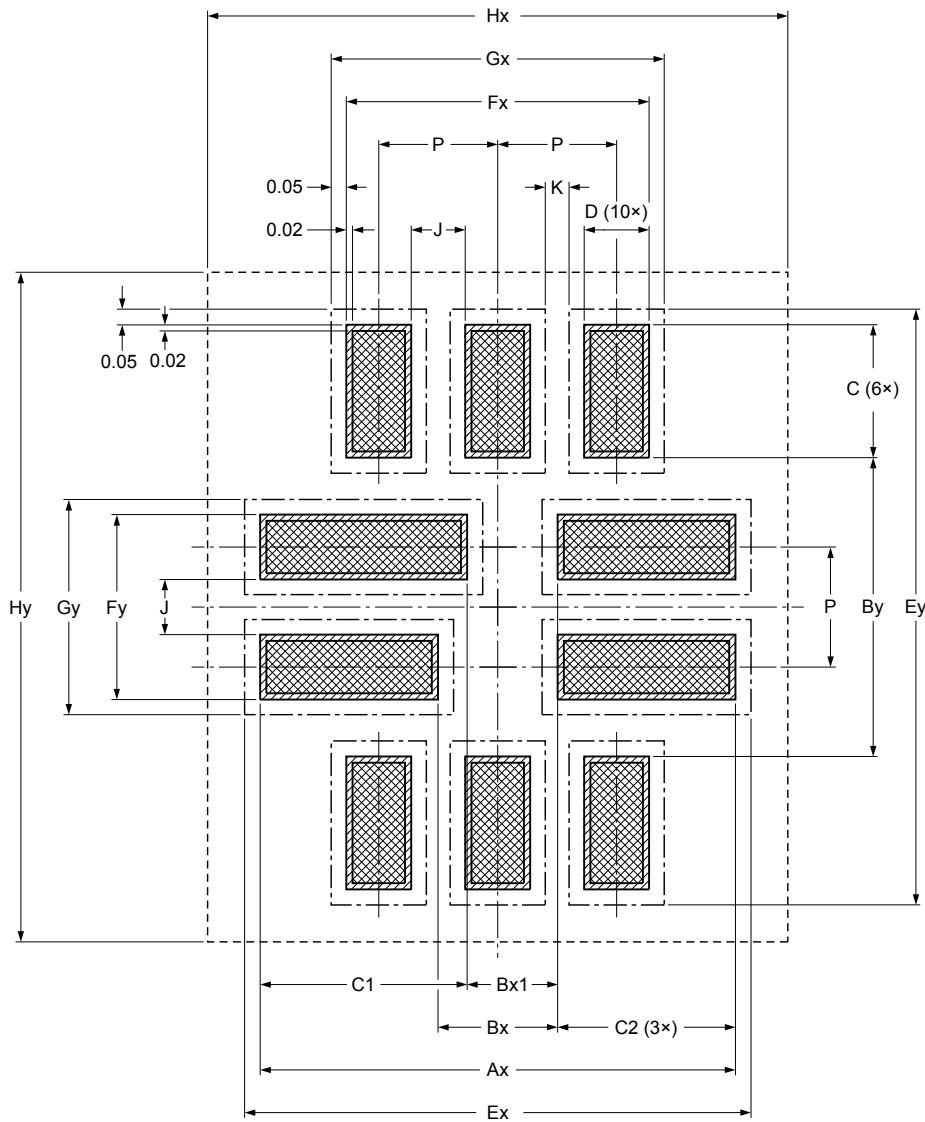
Fig. 1. Package outline XQFN10 (SOT1337-1)

plastic, extremely thin small outline package; 10 terminals; 0.4 mm pitch; 1.3 mm x 1.6 mm x 0.5 mm body

3. Soldering

Footprint information for reflow soldering of XQFN10 package

SOT1337-1



- occupied area
- solder resist
- solder lands
- solder paste

DIMENSIONS in mm

P	Ax	Bx	Bx1	By	C	C1	C2	D	Ex	Ey	Fx	Fy	Gx	Gy	Hx	Hy	J	K
0.4	1.6	0.4	0.3	1	0.45	0.7	0.6	0.22	1.7	2	1.02	0.62	1.12	0.72	1.95	2.25	0.18	0.08

Issue date ~~13-01-24~~
13-01-31

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Fig. 2. Reflow soldering footprint for XQFN10 (SOT1337-1)

plastic, extremely thin small outline package; 10 terminals; 0.4 mm pitch; 1.3 mm x 1.6 mm x 0.5 mm
body

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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